

Abstract

Base semiconductor component for a semiconductor component stack and method for the production thereof

The invention relates to a base semiconductor component (1) for a semiconductor component stack (2), wherein the base semiconductor component (1) has a semiconductor chip (3) arranged centrally on a stiff wiring substrate (4). The wiring substrate (4) has, in its edge regions (6, 7), contact pads (8) which are electrically connected to external contacts and at the same time to contact areas of the semiconductor chip (3) and also to stack contact areas (17). The stack contact areas (17) simultaneously form the upper side of the base semiconductor component (1) and have an arrangement pattern (16) corresponding to an arrangement pattern of external contacts (18) of a semiconductor component (19) to be stacked.

[Figure 1]